

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 2, line 1 with the following amended paragraph:

Fibrous fillers including glass fibers, which have conventionally been added so as to improve mechanical properties and heat resistance of a resin composition, had a problem such as difference in properties, particularly linear expansion coefficient, between molded article obtained in a flow direction during molding and a molded article obtained in a direction perpendicular to the flow direction (anisotropy). It is known to use, as the filler for solving the problem, boehmite having an external size of 0.5 to 15 μm (500 nm to 1500 15000 nm) and an aspect ratio of 10 to 100 and to use a phenol resin as the resin (Japanese Unexamined Patent Publication (Kokai) No. 2001-261976). However, thermal conductivity, mechanical strength, kneading workability and moldability of these compositions remain to be improved.

Please replace the paragraph beginning at page 3, line 22 with the following amended paragraph:

That is, the phenol resin composition of the present invention comprises a phenol resin and acicular or cylindrical boehmite having an average particle diameter (minor diameter) of 100 nm or less.

Please replace the paragraph beginning at page 3, line 26 with the following amended paragraph:

The resin composition containing a phenol resin and a benzooxazine resin of the present invention comprises a phenol resin and a benzooxazine resin in a weight ratio within a range from 95/5 to 25/75, and further comprises acicular or cylindrical boehmite having an average particle diameter (minor diameter) of 100 nm or less.

Please replace the paragraph beginning at page 3, line 34 with the following amended paragraph:

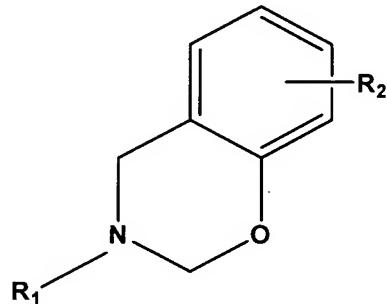
The phenol resin composition of the present invention has mechanical strength and thermal conductivity improved by mixing with acicular or cylindrical boehmite having an average particle diameter (minor diameter) of 100 nm or less, as compared with a conventional phenol resin composition, and is therefore preferably used for mechanical components, laminates and sheet materials, including molding materials for electrical and electronic components such as semiconductor sealing materials as well as molding materials for automobile components.

Please replace the paragraph beginning at page 4, line 28 with the following amended paragraph:

The boehmite used in the present invention is an inorganic compound represented by the general formula: AlO(OH) which contains at least 90% or more aluminum hydroxide oxide. In the present invention, fine boehmite having an average particle diameter (minor diameter) of 100 nm or less is used. The average particle diameter is preferably from 1 to 100 nm, more preferably from 5 to 50 nm, and most preferably from 10 to 20 nm. ~~The shape of the boehmite is not specifically limited and those having various shapes such as spherical, flat, acicular, cylindrical and amorphous are used.~~ In view of availability and an increase in mechanical strength, the shape of boehmite is acicular or cylindrical boehmite is preferable. Furthermore, an aspect ratio (= average particle diameter of major diameter/average particle diameter of minor diameter) is preferably from 1 to 100, and more preferably from 5 to 50. In the present invention, boehmite having a size of 100 nanometers or less is referred to as "nanoalumina".

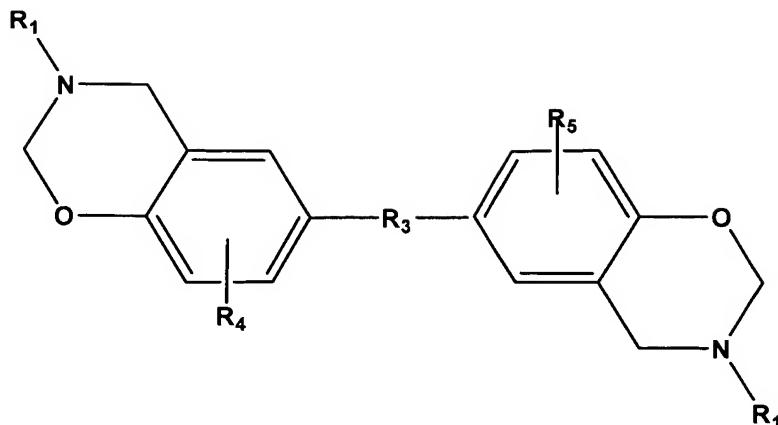
Please replace the paragraph beginning at page 6, line 11 and continuing to page 8, line 33 with the following amended paragraph:

Examples of the benzooxazine resin used in the present invention include thermosetting resins having a dihydrobenzooxazine ring in the molecule, for example, compounds represented by the following general formulas (1) to (4):



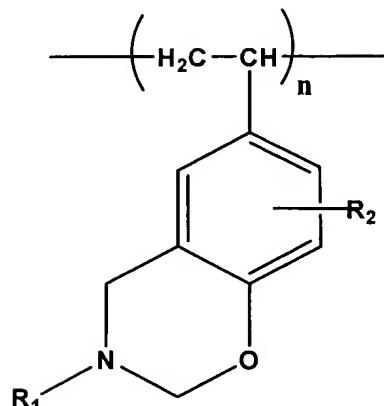
(1)

wherein R₁ represents alkyl group which may have a substituent, an aryl group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent or an aralkyl group which may have a substituent; and R₂ represents a hydrogen group, or an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkoxy group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent, an aralkyl group which may have a substituent, or those in which a halogen atom, a nitro group, a cyano group, an alkoxy carbonyl group, a hydroxyl group or an alkyl(aryl)sulfonyl group is monosubstituted, disubstituted, trisubstituted or tetrasubstituted;



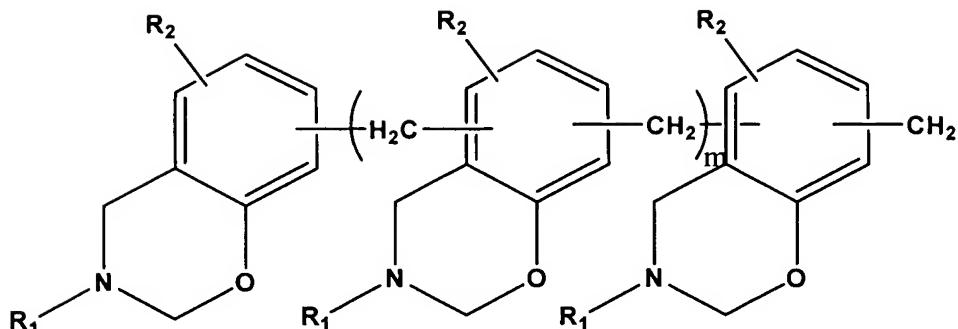
(2)

in the general formula (2), R₁ represents an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent or an aralkyl group which may have a substituent; R₃ represents a single bond or alkylene group which may have a substituent, an arylene group which may have a substituent, an alkenylene group which may have a substituent, an alkynylene group which may have a substituent, an aralkylene group which may have a substituent, or a carbonyl group, an ether group, a thioether group, a silylene group, a siloxane group, a methylene ether group, an ester group or a sulfonyl group; and R₄ and R₅ are the same or different and represent a hydrogen group, or an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkoxy group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent, an aralkyl group which may have a substituent, or those in which a halogen atom, a nitro group, a cyano group, an alkoxy carbonyl group, a hydroxyl group or an alkyl(aryl)sulfonyl group is monosubstituted, disubstituted or trisubstituted;



(3)

in the general formula (3), R₁ represents an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent or an aralkyl group which may have a substituent; R₂ represents a hydrogen group, or an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkoxy group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent, an aralkyl group which may have a substituent, or a halogen atom, a nitro group, a cyano group, an alkoxy carbonyl group, a hydroxyl group or an alkyl(aryl)sulfonyl group; and n represents an integer of 2 to 200; and



(4)

in the general formula (4), R₁ represents an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent or an aralkyl group which may have a substituent; R₂ represents a hydrogen group, or an alkyl group which may have a substituent, an aryl group which may have a substituent, an alkoxy group which may have a substituent, an alkenyl group which may have a substituent, an alkynyl group which may have a substituent, an aralkyl group which may have a substituent, or a halogen atom, a nitro group, a cyano group, an alkoxycarbonyl group, a hydroxyl group or an alkyl(aryl)sulfonyl group; and m represents an integer of 0 to 100.

Please replace the paragraph beginning at page 16, line 5 with the following amended paragraph:

In the same manner as in Example 3, except that the formulation was replaced by that shown in Table 1, resin compositions and specimens were obtained and performances were evaluated. The results are shown in Table 1. In Comparative Example 2, Serasyuru BMB manufactured by Kawai Lime Industry Co., Ltd. {average particle diameter (minor diameter): 1 μ m, aspect ratio: 2} was used as boehmite. In Comparative Examples 1 and 2-3, no boehmite was used. In Comparative Example 3, a chopped strand of ECS03-167S, manufactured by Central Glass Co., Ltd., was used as glass fibers.